

	Type	Hit s	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De ni ti on	Er ro r ro rs	Ref #
1	BRS	464	partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:19				S1
2	BRS	157	partial\$4 with (bond\$4 or join\$4) with wafer same (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:04				S2
3	BRS	119	partial\$4 with (bond\$4 or join\$4) with wafer with (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:05				S3
4	BRS	69	partial\$4 with (bond\$4 or join\$4) with wafer with (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:06				S4
5	BRS	38	partial\$4 with (bond\$4 or join\$4) with wafer with (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and chip and align\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:06				S5

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6	BRS	22	partial\$4 with (bond\$4 or join\$4) with wafer with (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and chip and align\$5 and (cmp or polish\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:07				S6
7	BRS	90	partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:10				S7
8	BRS	203	("438"/\$).ccls. and partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:10				S9
9	BRS	37	("438"/\$).ccls. and partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:10				S10

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10	BRS	26	partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5 and chip and align\$5 and (cmp or polish\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:11				S8
11	BRS	7	("438"/\$).ccls. and partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5 and chip and align\$5 and (cmp or polish\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/26 12:59				S11
12	BRS	142	partial\$4 with (bond\$4 or join\$4) near wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:33				S12
13	BRS	51	partial\$4 with (bond\$4 or join\$4) near wafer same (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:20				S13

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14	BRS 151	(bond\$4 or join\$4) near wafer same (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5 and chip and align\$5 and (cmp or polish\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:34				S14
15	BRS 15	(bond\$4 or join\$4) near wafer same (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5 and chip and align\$5 and (cmp or polish\$4) and oxide near bond\$4	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/26 13:53				S15
16	BRS 9	("438"/464).ccls. and partial\$4 with (bond\$4 or join\$4) with wafer	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/26 13:23				S16
17	BRS 21	("3332137" "3475664"   "3579055"   "3623219" "3832247"   "5091331"   "5169472" "5183769" "5385632").PN. OR ("5654226").URPN.	US - PGPUB; USPAT; USOCR	2005/06/26 13:12				S17

	Type	Hit s	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fin iti on	Er ro r De fin iti on	Ref #
18	BRS	78	("438"/464).ccls. and (bond\$4 or join\$4) near wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/26 13:24				S18
19	BRS	1	("438"/464).ccls. and (bond\$4 or join\$4) near wafer and (saw\$ or dic\$4) and seperat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/27 03:40				S20
20	BRS	54	("438"/464).ccls. and (bond\$4 or join\$4) near wafer and (saw\$ or dic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/26 13:28				S19
21	BRS	33	("4121334" "4784970" "4975390").PN. OR ("5091331").URPN.	US-PGPUB; USPAT; USOCR	2005/06/26 13:38				S21
22	BRS	528 761	(bond\$4 or join\$4) near wafer same (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5 and chip and align\$5 and (cmp or polish\$4) and oxide near bond\$4 rough\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/26 13:54				S22

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23	BRS	15	(bond\$4 or join\$4) near wafer same (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5 and chip and align\$5 and (cmp or polish\$4) and oxide near bond\$4 and rough\$	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/26 14:04				S23
24	BRS	126	(bond\$4 or join\$4) near wafer same (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and roughen\$	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/26 14:05				S24
25	BRS	3	(bond\$4 or join\$4) near wafer with roughen\$ same (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/26 14:05				S25

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comm en ts	Error r De fi ni ti on	Error rs
1	BRS	L2	1	("438"/458).ccls. and (bond\$4 or join\$4) near wafer and (saw\$ or dic\$4) and seperat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/27 03:41			
2	BRS	L3	0	("438"/456).ccls. and (bond\$4 or join\$4) near wafer and (saw\$ or dic\$4) and seperat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/27 03:41			
3	BRS	L4	0	("438"/459).ccls. and (bond\$4 or join\$4) near wafer and (saw\$ or dic\$4) and seperat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/27 03:41			
4	BRS	L5	1	("438"/977).ccls. and (bond\$4 or join\$4) near wafer and (saw\$ or dic\$4) and seperat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/27 03:41			
5	BRS	L6	0	("438"/421).ccls. and (bond\$4 or join\$4) near wafer and (saw\$ or dic\$4) and seperat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/27 03:41			